

HDAM SERIES

(2.00 mm) .0787"

RUGGED ELEVATED HIGH-DENSITY ARRAY

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAM

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Current Rating:

3.4 A per pin

(6 adjacent pins powered)

Operating Temp Range:

-55 °C to +125 °C

Working Voltage:

200 VAC

Mated Cycles:

100

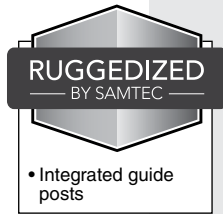
RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

Mates with:
HDAF



Intermateable with
Molex HD Mezz

Open-pin-field for
Single-Ended
or Differential Pair
configurations

Lead-Free
Solder Charge

299, 195
and 143 pins

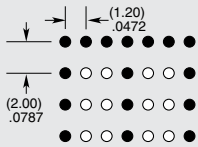
Elevated stack heights
of 20 mm, 25 mm,
30 mm and 35 mm

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

*2:1 S:G Ratio

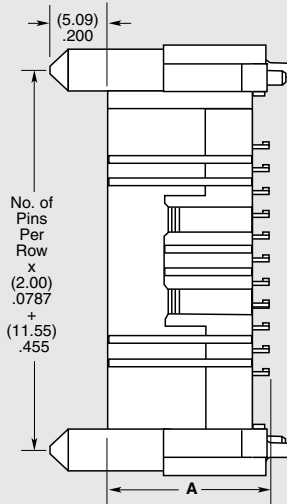
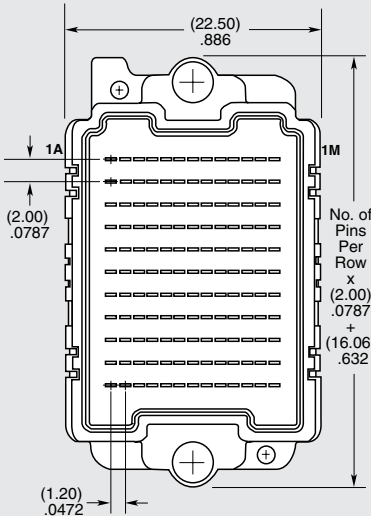
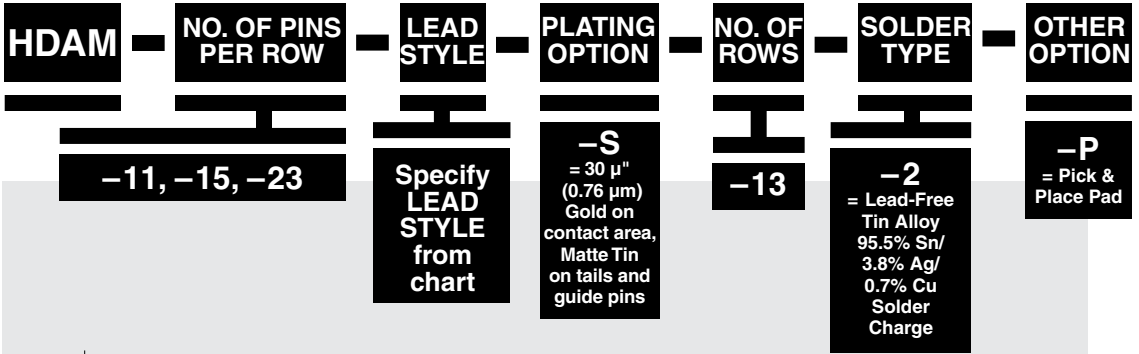
ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
- Other platings
- Contact Samtec.

Notes:

HD Mezz is a trademark of Molex Incorporated

Note: Some lengths, styles and options are non-standard, non-returnable.



LEAD STYLE	A
-12.0	(14.41) .567
-17.0	(19.41) .764

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.